### INTEGRATED CIRCUITS

# DATA SHEET

## 74F193

Up/down binary counter with separate up/down clocks

Product specification

1995 Jul 17

IC15 Data Handbook





### Up/down binary counter with separate up/down clocks

74F193

#### **FEATURES**

- Synchronous reversible 4-bit counting
- Asynchronous parallel load capability
- Asynchronous reset (clear)
- Cascadable without external logic

#### **DESCRIPTION**

The 74F193 is a 4-bit synchronous up/down counter in the binary mode. Separate up/down clocks,  $\text{CP}_{\text{U}}$  and  $\text{CP}_{\text{D}}$  respectively, simplify operation. The outputs change state synchronously with the Low-to-High transition of either clock input. If the  $\text{CP}_{\text{U}}$  clock is pulsed while  $\text{CP}_{\text{D}}$  is held High, the device will count up. If  $\text{CP}_{\text{D}}$  clock is pulsed while  $\text{CP}_{\text{U}}$  is held High, the device will count down. The device can be cleared at any time by the asynchronous reset pin. It may also be loaded in parallel by activating the asynchronous parallel load pin.

Inside the device are four master-slave JK flip-flops with the necessary steering logic to provide the asynchronous reset, asynchronous preset, load, and synchronous count up and count down functions.

Each flip-flop contains JK feedback from slave to master, such that a Low-to-High transition on the  $\mbox{CP}_{\mbox{D}}$  input will decrease the count by one, while a similar transition on the  $\mbox{CP}_{\mbox{U}}$  input will advance the count by one.

One clock should be held High while counting with the other, because the circuit will either count by twos or not at all, depending on the state of the first JK flip-flop, which cannot toggle as long as either clock input is Low. Applications requiring reversible operation must make the reversing decision while the activating clock is High to avoid erroneous counts.

The Terminal Count Up  $(\overline{TC}_U)$  and Terminal Count Down  $(\overline{TC}_D)$  outputs are normally High. When the circuit has reached the maximum count state of 15, the next High-to-Low transition of  $CP_U$  will cause  $\overline{TC}_U$  to go Low.  $\overline{TC}_U$  will stay Low until  $CP_U$  goes High again, duplicating the count up clock, although delayed by two gate delays. Likewise, the  $\overline{TC}_D$  output will go Low when the circuit is in the zero state and the  $CP_D$  goes Low. The  $\overline{TC}$  outputs can be used as the clock input signals to the next higher order circuit in a multistage counter, since they duplicate the clock waveforms.

Multistage counters will not be fully synchronous since there is a two-gate delay time difference added for each stage that is added.

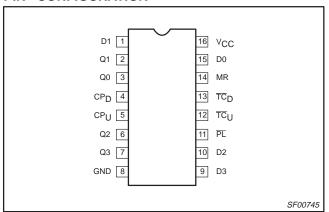
The counter may be preset by the asynchronous parallel load capability of the circuit. Information present on the parallel Data inputs (D0 - D3) is loaded into the counter and appears on the outputs regardless of the conditions of the clock inputs when the Parallel Load ( $\overline{PL}$ ) input is Low. A High level on the Master Reset (MR) input will disable the parallel load gates, override both clock inputs, and set all Q outputs Low. If one of the clock inputs is Low during and after a reset or load operation, the next Low-to-High transition of the clock will be interpreted as a legitimate signal and will be counted.

TYPE	TYPICAL f <sub>MAX</sub>	TYPICAL SUPPLY CURRENT (TOTAL)
74F193	125MHz	32mA

#### ORDERING INFORMATION

DESCRIPTION	COMMERCIAL RANGE $V_{CC}$ = 5V $\pm 10\%$ , $T_{amb}$ = 0°C to +70°C	PKG DWG #		
16-pin plastic DIP	N74F193N	SOT38-4		
16-pin plastic SO	N74F193D	SOT109-1		

#### PIN CONFIGURATION



### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

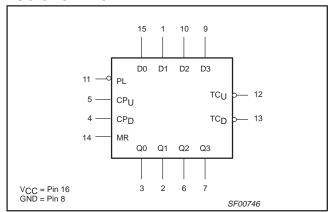
PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
D0 - D3	Data inputs	1.0/1.0	20μA/0.6mA
CPU	Count up clock input (active rising edge)	1.0/3.0	20μA/1.8mA
CPD	Count down clock input (active rising edge)	1.0/3.0	20μA/1.8mA
PL	Asynchronous parallel load control input (active Low)	1.0/1.0	20μA/0.6mA
MR	Asynchronous master reset input	1.0/1.0	20μA/0.6mA
Q0 - Q3	Flip-flop outputs	50/33	1.0mA/20mA
TC <sub>U</sub>	Terminal count up (carry) output (active Low)	50/33	1.0mA/20mA
TCD	Terminal count down (borrow) output (active Low)	50/33	1.0mA/20mA

NOTE: One (1.0) FAST Unit Load (U.L.) is defined as: 20μA in the High state and 0.6mA in the Low state.

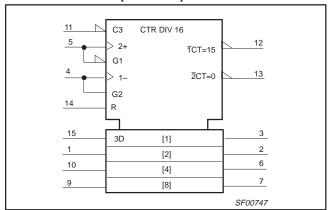
### Up/down binary counter with separate up/down clocks

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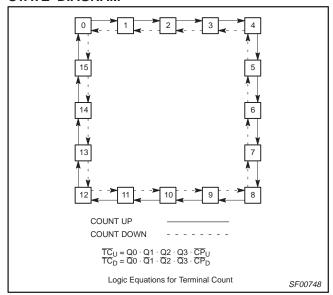
### LOGIC SYMBOL



### LOGIC SYMBOL (IEEE/IEC)



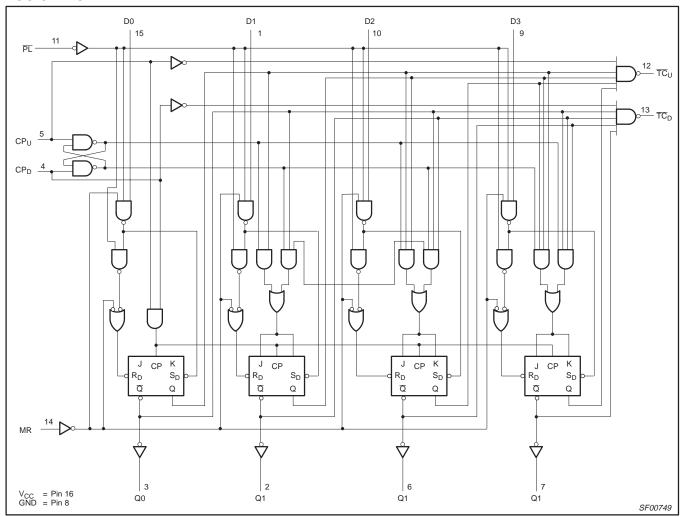
### STATE DIAGRAM



### Up/down binary counter with separate up/down clocks

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### **LOGIC DIAGRAM**



### **FUNCTION TABLE**

			INP	UTS				OUTPUTS						OPERATING
MR	PL	CPU	CPD	D0	D1	D2	D3	Q0	Q1	Q2	Q3	TCU	TCD	MODE
Н	Х	Х	L	Х	Х	Х	Х	L	L	L	L	Н	L	Reset (clear)
Н	Х	Х	Н	Х	Х	Х	Х	L	L	L	L	Н	Н	
L	L	Х	L	L	L	L	L	L	L	L	L	Н	L	
L	L	Х	Н	L	L	L	L	L	L	L	L	Н	Н	Parallel load
L	L	L	Х	Н	Н	Н	Н	Н	Н	Н	Н	L	Н	
L	L	Н	Х	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	
L	Н	<b>↑</b>	Н	Х	Х	Х	Х	Count up		H <sup>1</sup>	Н	Count up		
L	Н	Н	1	Х	Х	Х	Х	Count down			Н	H <sup>2</sup>	Count down	

H = High voltage level
L = Low voltage level

= Don't care

= Low-to-High clock transition

 $\overline{TC}_U = \overline{CP}_U$  at terminal count up (HHHH)  $\overline{TC}_D = \overline{CP}_D$  at terminal count down (LLLL)

### Up/down binary counter with separate up/down clocks

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#### ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	−30 to +5.0	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	−0.5 to +V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	40	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature	-65 to +150	°C

#### RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		UNIT		
STWIBUL	PARAMETER	MIN	NOM	MAX	UNII
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
Іон	High-level output current			-1	mA
I <sub>OL</sub>	Low-level output current			20	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

						LIMITS		
SYMBOL	PARAMETER	2	TEST CONDITIONS <sup>N</sup>	IO TAG	MIN	TYP NO TAG	MAX	UNIT
Vari	High-level output voltage		V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX,	±10%V <sub>CC</sub>	2.5			V
V <sub>OH</sub>	High-level output voltage		I <sub>OH</sub> = MAX, V <sub>IH</sub> = MIN	2.7	3.4		V	
V	Low lovel output voltage		V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX,	±10%V <sub>CC</sub>		0.35	0.50	V
V <sub>OL</sub>	Low-level output voltage		I <sub>OL</sub> = MAX, V <sub>IH</sub> = MIN		0.35	0.50	V	
V <sub>IK</sub>	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V	
I <sub>I</sub>	Input current at maximum input voltage		$V_{CC} = MAX, V_I = 7.0V$				100	μΑ
I <sub>IH</sub>	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
I <sub>IL</sub>	Low-level input	CP <sub>U</sub> , CP <sub>D</sub>	V MAY V OFV				-1.8	mA
	current Others		$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
I <sub>OS</sub>	Short-circuit output curren	tNO TAG	$V_{CC} = MAX$	-60		-150	mA	
Icc	Supply current (total) <sup>4</sup>		V <sub>CC</sub> = MAX		32	50	mA	

1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

All typical values are at  $V_{CC} = 5V$ ,  $T_{amb} = 25^{\circ}C$ .

Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

4. Measure I<sub>CC</sub> with parallel load and Master reset inputs grounded, all other inputs at 4.5V and all outputs open.

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### **AC ELECTRICAL CHARACTERISTICS**

					LIMIT	s		
SYMBOL	PARAMETER	TEST CONDITIONS	v	<sub>amb</sub> = +25° <sub>CC</sub> = +5.0 i0pF, R <sub>L</sub> =	V	T <sub>amb</sub> = 0°( V <sub>CC</sub> = +5. C <sub>L</sub> = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
$f_{MAX}$	Maximum clock frequency	Waveform 1	100	125		90		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay $CP_U$ or $CP_D$ to $CP_U$ or $CP_D$	Waveform 2	2.5 3.0	5.5 5.0	8.5 8.0	2.5 3.0	9.0 9.0	ns ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay CP <sub>U</sub> or CP <sub>D</sub> to Qn	Waveform 1	2.5 5.0	5.5 8.5	8.5 12.0	2.5 5.0	9.0 13.0	ns ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay D <sub>n</sub> to Qn	Waveform 4	2.0 6.0	4.0 9.5	7.0 13.5	1.5 6.0	8.0 15.0	ns ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay PL to Qn	Waveform 3	4.5 5.5	6.5 8.5	10.0 12.0	4.0 5.0	11.0 13.0	ns ns
t <sub>PHL</sub>	Propagation delay MR to Qn	Waveform 5	5.0	7.5	11.0	5.0	12.0	ns
t <sub>PLH</sub>	Propagation delay MR to TC <sub>U</sub>	Waveform 5	6.0	8.5	12.0	5.5	13.0	ns
t <sub>PHL</sub>	Propagation delay MR to TC <sub>D</sub>	Waveform 5	5.0	7.5	11.0	5.0	12.0	ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay PL to TC <sub>U</sub> or TC <sub>D</sub>	Waveform 3	6.0 6.0	9.5 9.0	13.5 12.0	6.0 6.0	15.0 13.0	ns ns
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay Dn to TC <sub>U</sub> or TC <sub>D</sub>	Waveform 4	5.5 4.5	9.0 8.5	13.0 12.5	5.0 4.5	14.0 13.5	ns ns

### **AC SETUP REQUIREMENTS**

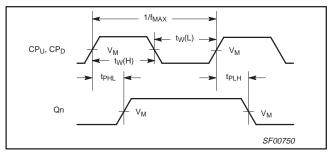
					LIMIT	s		
SYMBOL	PARAMETER	TEST CONDITIONS	V	<sub>mb</sub> = +25° <sub>CC</sub> = +5.0° opF, R <sub>L</sub> =	V	T <sub>amb</sub> = 0°C V <sub>CC</sub> = +5. C <sub>L</sub> = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
t <sub>s</sub> (H) t <sub>s</sub> (L)	Setup time, High or Low Dn to PL	Waveform 6	4.5 4.5			5.0 5.0		ns ns
t <sub>h</sub> (H) t <sub>h</sub> (L)	Hold time, High or Low Dn to PL	Waveform 6	2.0 2.0			2.0 2.0		ns ns
t <sub>w</sub> (L)	PL Pulse width Low	Waveform 3	6.0			6.0		ns
t <sub>w</sub> (H) t <sub>w</sub> (L)	CP <sub>U</sub> or CP <sub>D</sub> Pulse width High or Low	Waveform 1	3.5 5.0			3.5 5.0		ns ns
t <sub>w</sub> (L)	CP <sub>U</sub> or CP <sub>D</sub> Pulse width Low (Change of direction)	Waveform 1	10.0			10.0		ns
t <sub>w</sub> (H)	MR Pulse width High	Waveform 5	6.0			6.0		ns
t <sub>rec</sub>	Recovery time, PL to CP <sub>U</sub> or CP <sub>D</sub>	Waveform 3	6.0			6.0		ns
t <sub>rec</sub>	Recovery time MR to CP <sub>U</sub> or CP <sub>D</sub>	Waveform 5	4.0			4.0		ns

### Up/down binary counter with separate up/down clocks

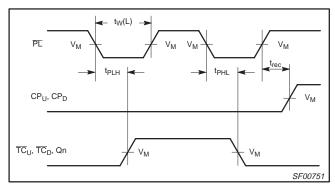
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#### **AC WAVEFORMS**

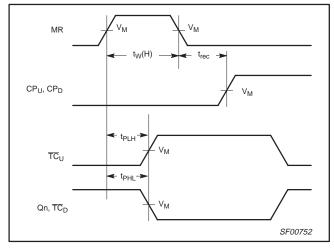
For all waveforms Vm = 1.5V



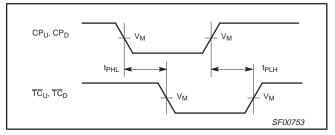
Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width and Maximum Clock Frequency



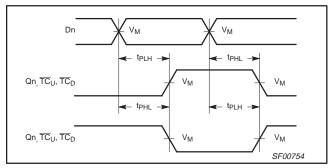
Waveform 3. Parallel Pulse Width,
Parallel Load to Output Delays, and Parallel Load
to Clock Recovery Time



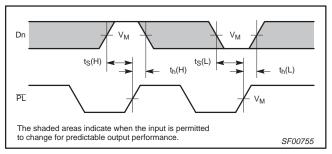
Waveform 5. Master Reset Pulse Width, Master Reset to Output Delay and Master Reset to Clock Recovery Time



Waveform 2. Propagation Delay, Clock to Terminal Count



Waveform 4. Propagation Delay, Data to Flip-Flop Outputs, Terminal Count Up and Down Outputs



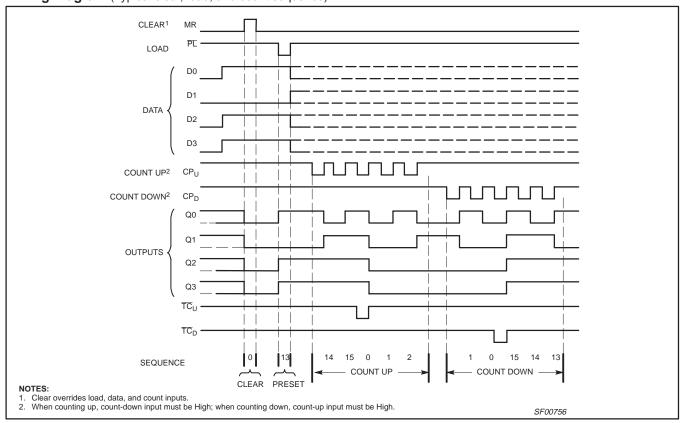
Waveform 6. Data Setup and Hold Times

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### Up/down binary counter with separate up/down clocks

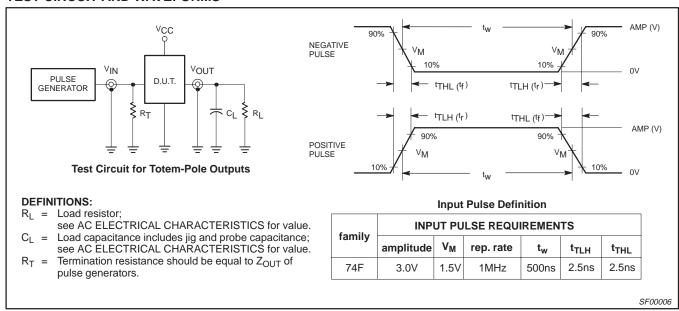
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### Timing Diagram (Typical clear, load, and count sequence)



### **Binary Counter**

### **TEST CIRCUIT AND WAVEFORMS**

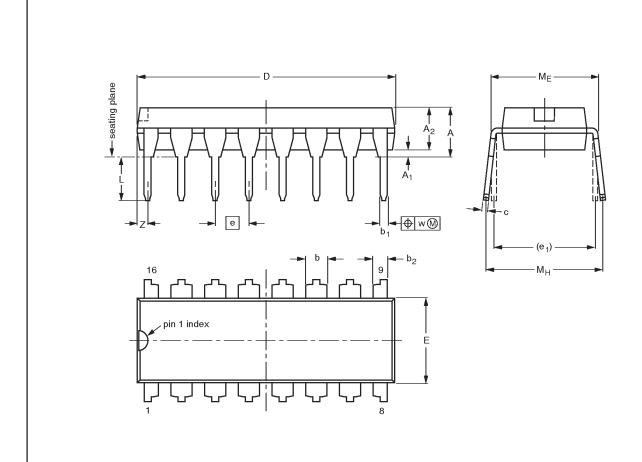


### Up/down binary counter with separate up/down clocks

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### DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4





### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER		EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	PROJECTION	ISSUE DATE		
SOT38-4					□ •	<del>92-11-17</del> 95-01-14

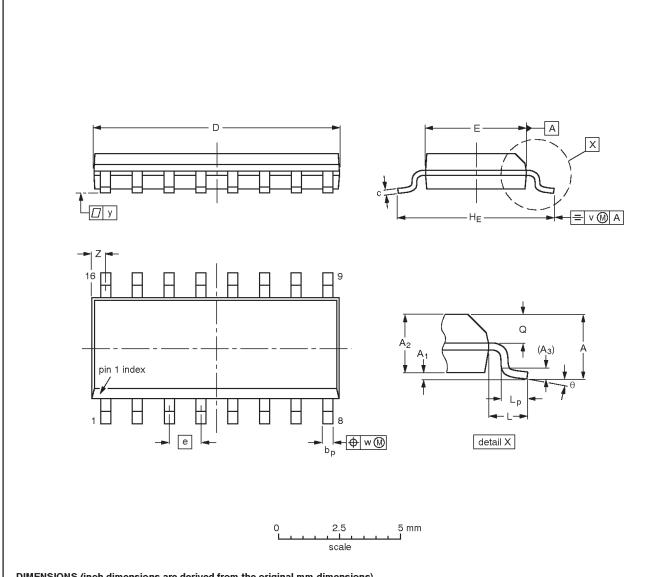
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### Up/down binary counter with separate up/down clocks

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### SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.39 0.38	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016		0.01	0.01	0.004	0.028 0.012	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT109-1	076E07S	MS-012AC				<del>95-01-23</del> 97-05-22

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### Up/down binary counter with separate up/down clocks

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### **NOTES**

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### Up/down binary counter with separate up/down clocks

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#### Data sheet status

Data sheet status	Product status	Definition [1]	
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.	
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.	
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible produc	

<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

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**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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